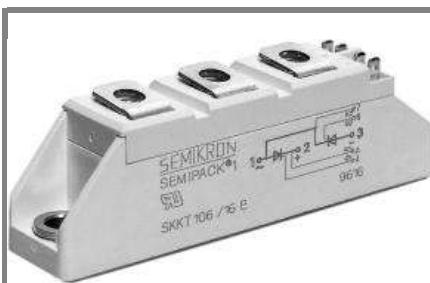


SKKT 92, SKKH 92, SKKT 92B THYRISTOR



SEMIPACK® 1

Thyristor / Diode Modules

SKKT 92

SKKT 92B

SKKH 92

Features

- Heat transfer through aluminium oxide ceramic isolated metal baseplate
- Hard soldered joints for high reliability
- UL recognized, file no. E 63 532

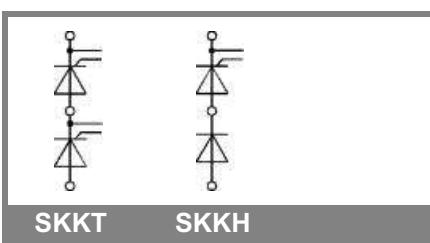
Typical Applications

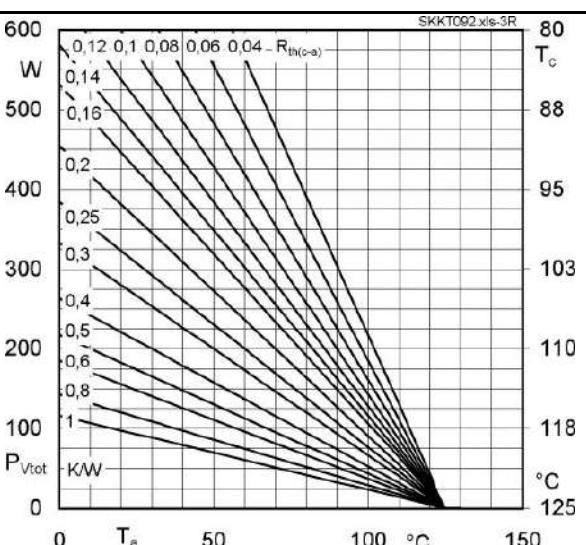
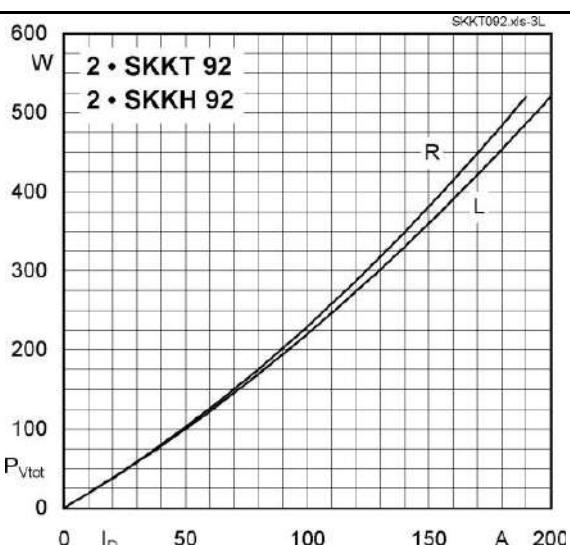
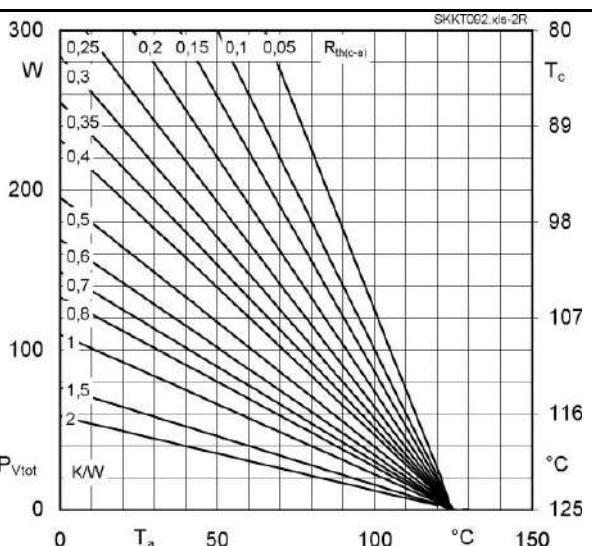
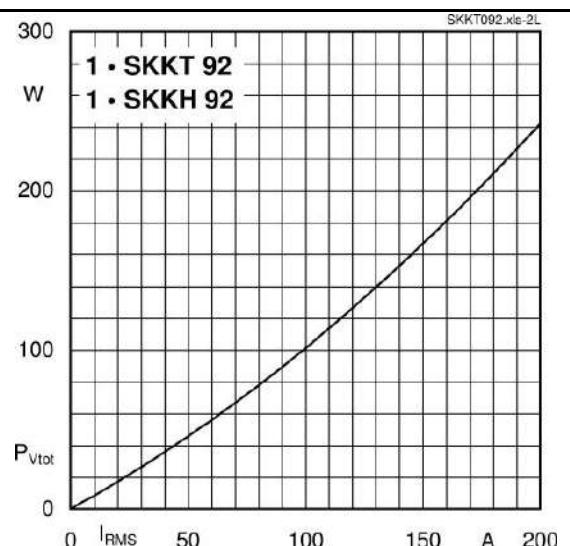
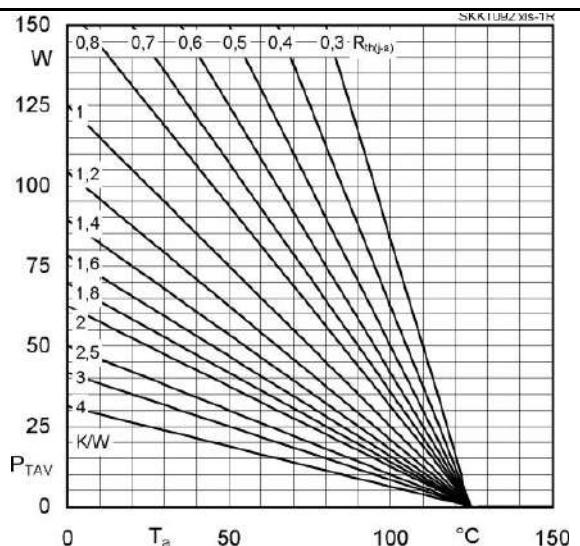
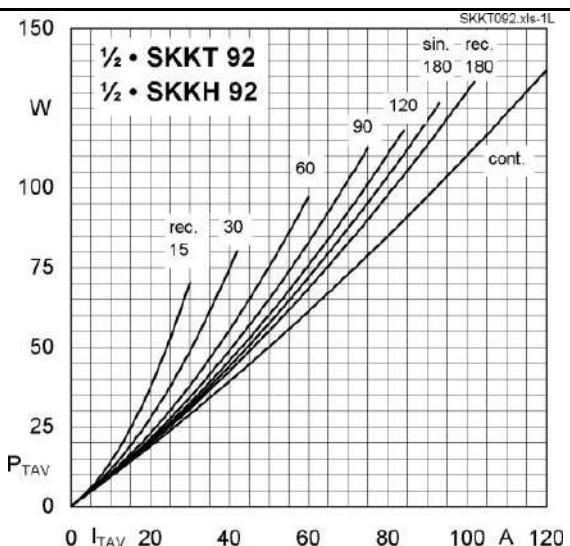
- DC motor control (e. g. for machine tools)
- AC motor soft starters
- Temperature control (e. g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)

¹⁾ See the assembly instructions

V_{RSM}	V_{RRM}, V_{DRM}	$I_{TRMS} = 150 \text{ A}$ (maximum value for continuous operation) $I_{TAV} = 95 \text{ A}$ (sin. 180; $T_c = 85^\circ\text{C}$)		
V 900	V 800	SKKT 92/08E	SKKT 92B08E	SKKH 92/08E
1300	1200	SKKT 92/12E	SKKT 92B12E	SKKH 92/12E
1500	1400	SKKT 92/14E	SKKT 92B14E	SKKH 92/14E
1700	1600	SKKT 92/16E	SKKT 92B16E	SKKH 92/16E
1900	1800	SKKT 92/18E	SKKT 92B18E	SKKH 92/18E

Symbol	Conditions	Values	Units
I_{TAV}	sin. 180; $T_c = 85$ (100) $^\circ\text{C}$; P3/180; $T_a = 45^\circ\text{C}$; B2 / B6	95 (68)	A
I_D	P3/180F; $T_a = 35^\circ\text{C}$; B2 / B6	70 / 85	A
I_{RMS}	P3/180F; $T_a = 35^\circ\text{C}$; W1 / W3	140 / 175	A
I_{TSM}	$T_{vj} = 25^\circ\text{C}$; 10 ms $T_{vj} = 125^\circ\text{C}$; 10 ms	190 / 3 * 135	A
i^2t	$T_{vj} = 25^\circ\text{C}$; 8,3 ... 10 ms $T_{vj} = 125^\circ\text{C}$; 8,3 ... 10 ms	2000 1750 20000 15000	A ² s
V_T	$T_{vj} = 25^\circ\text{C}$; $I_T = 300 \text{ A}$	max. 1,65	V
$V_{T(TO)}$	$T_{vj} = 125^\circ\text{C}$	max. 0,9	V
r_T	$T_{vj} = 125^\circ\text{C}$	max. 2	mΩ
$I_{DD}; I_{RD}$	$T_{vj} = 125^\circ\text{C}$; $V_{RD} = V_{RRM}$; $V_{DD} = V_{DRM}$	max. 20	mA
t_{gd}	$T_{vj} = 25^\circ\text{C}$; $I_G = 1 \text{ A}$; $dI_G/dt = 1 \text{ A}/\mu\text{s}$	1	μs
t_{gr}	$V_D = 0,67 * V_{DRM}$	2	μs
$(di/dt)_{cr}$	$T_{vj} = 125^\circ\text{C}$	max. 150	A/μs
$(dv/dt)_{cr}$	$T_{vj} = 125^\circ\text{C}$	max. 1000	V/μs
t_q	$T_{vj} = 125^\circ\text{C}$,	100	μs
I_H	$T_{vj} = 25^\circ\text{C}$; typ. / max.	150 / 250	mA
I_L	$T_{vj} = 25^\circ\text{C}$; $R_G = 33 \Omega$; typ. / max.	300 / 600	mA
V_{GT}	$T_{vj} = 25^\circ\text{C}$; d.c.	min. 3	V
I_{GT}	$T_{vj} = 25^\circ\text{C}$; d.c.	min. 150	mA
V_{GD}	$T_{vj} = 125^\circ\text{C}$; d.c.	max. 0,25	V
I_{GD}	$T_{vj} = 125^\circ\text{C}$; d.c.	max. 6	mA
$R_{th(j-c)}$	cont.; per thyristor / per module	0,28 / 0,14	K/W
$R_{th(c-c)}$	sin. 180; per thyristor / per module	0,3 / 0,15	K/W
$R_{th(j-c)}$	rec. 120; per thyristor / per module	0,32 / 0,16	K/W
$R_{th(c-s)}$	per thyristor / per module	0,2 / 0,1	K/W
T_{vj}		- 40 ... + 125	°C
T_{stg}		- 40 ... + 125	°C
V_{isol}	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3600 / 3000	V~
M_s	to heatsink	5 ± 15 % ¹⁾	Nm
M_t	to terminals	3 ± 15 %	Nm
a		5 * 9,81	m/s ²
m	approx.	95	g
Case	SKKT SKKT ...B SKKH	A 46 A 48 A 47	





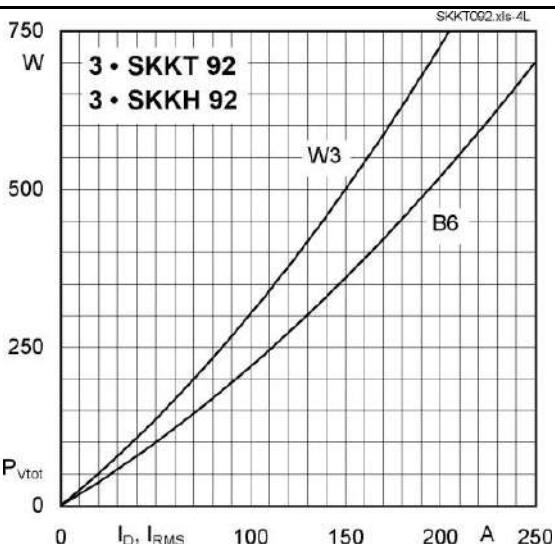


Fig. 4L Power dissipation of three modules vs. direct and rms current

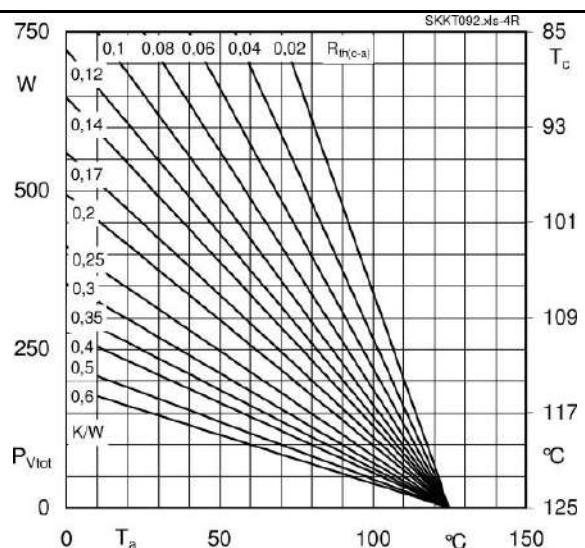


Fig. 4R Power dissipation of three modules vs. case temp.

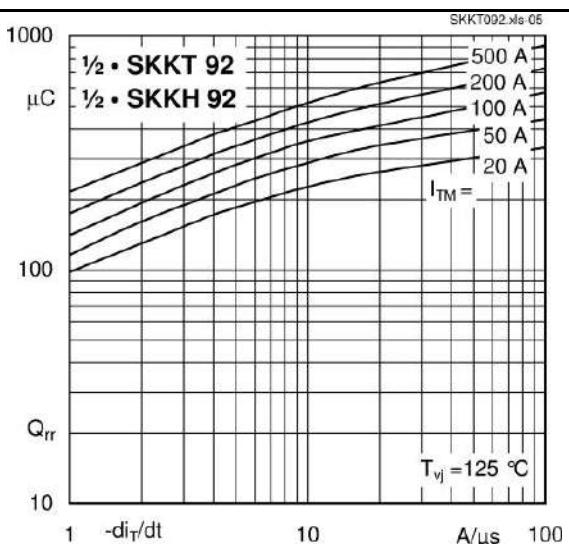


Fig. 5 Recovered charge vs. current decrease

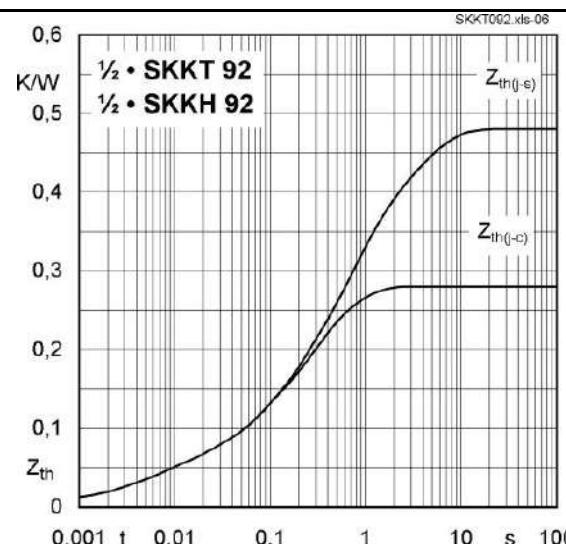


Fig. 6 Transient thermal impedance vs. time

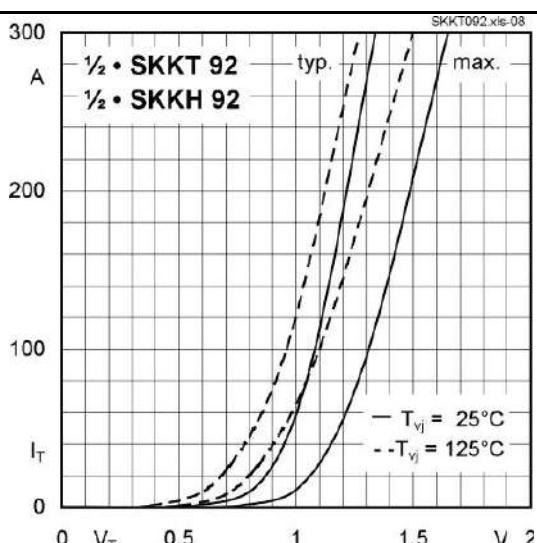


Fig. 7 On-state characteristics

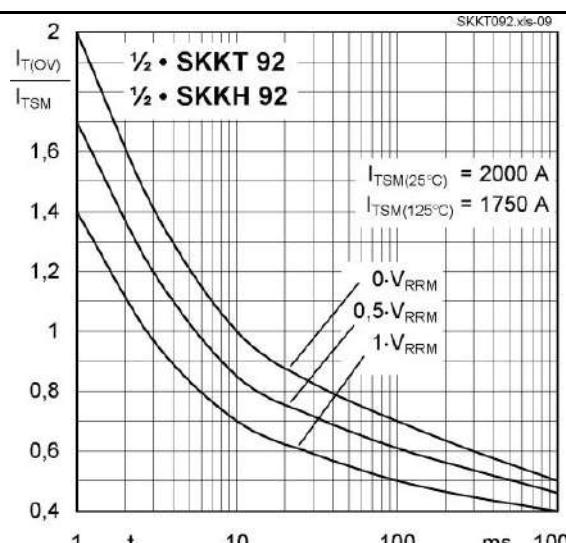
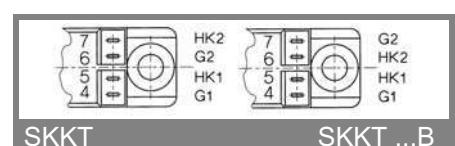
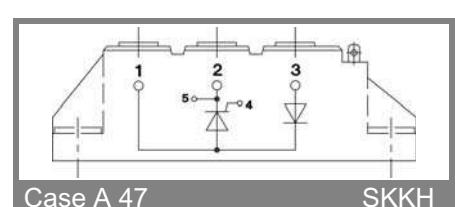
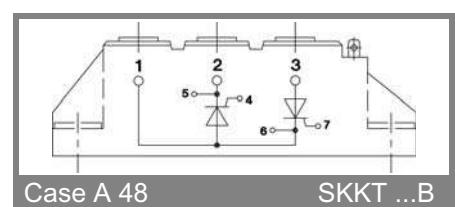
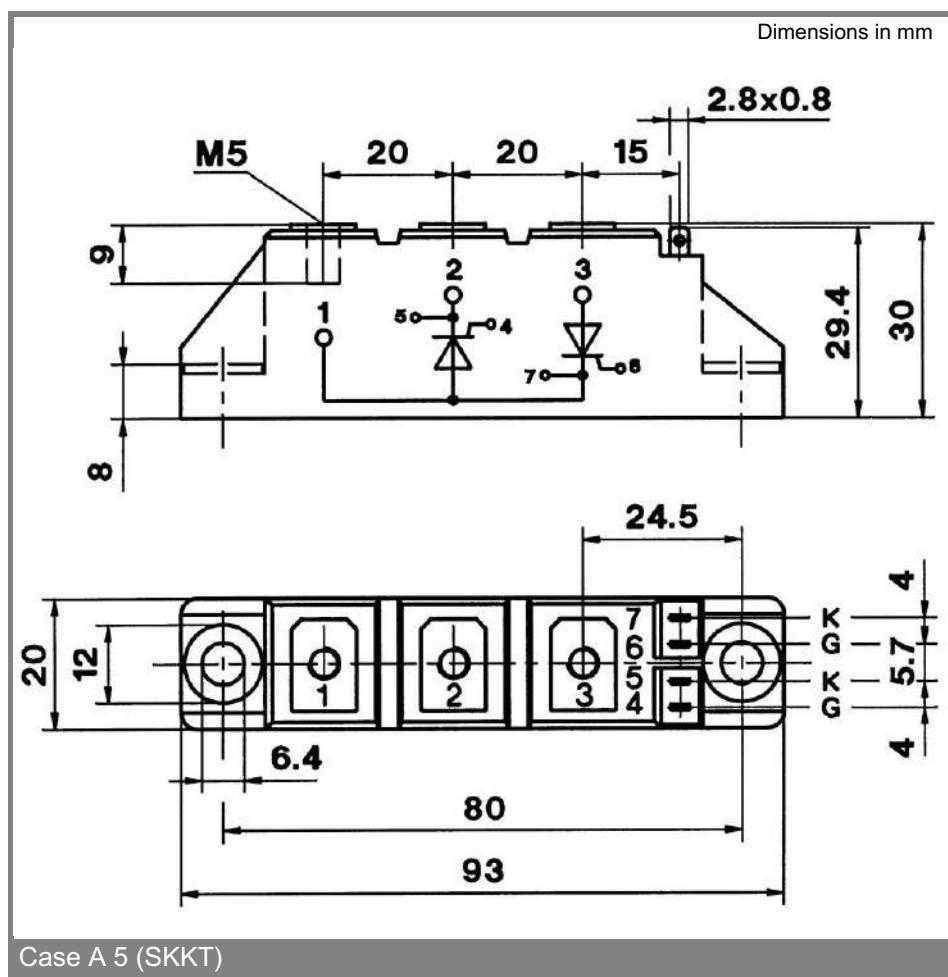
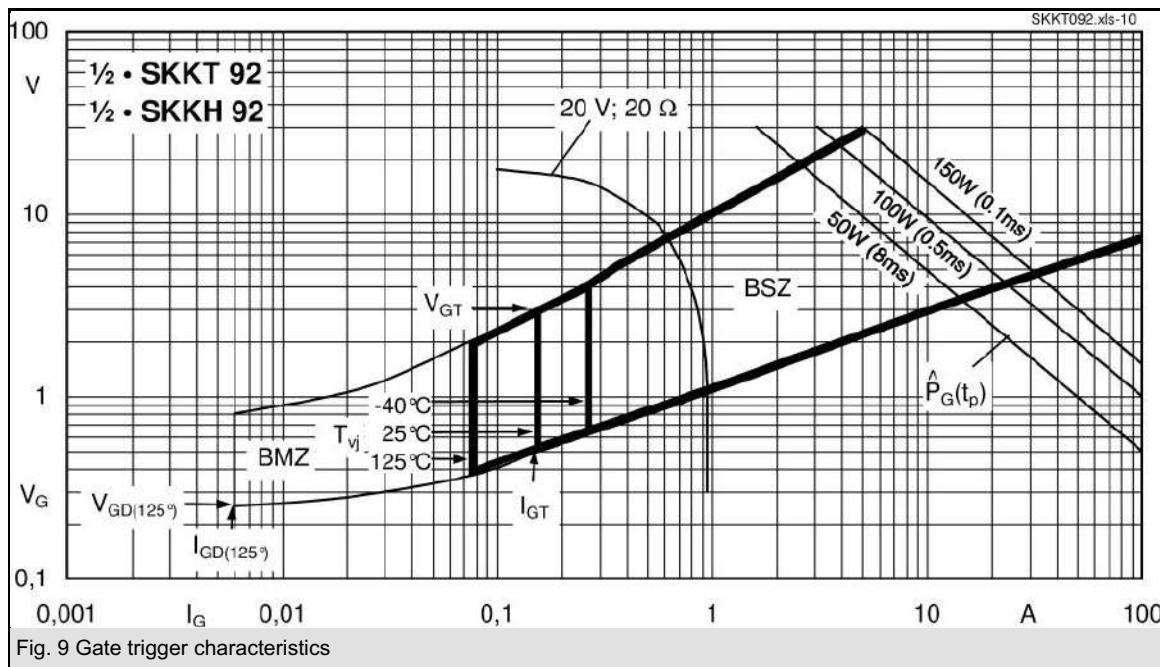


Fig. 8 Surge overload current vs. time



This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.

Thyristor \ Diode Module

$V_{RRM} = 2 \times 1600 \text{ V}$

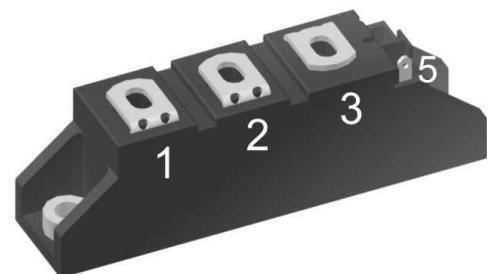
$I_{TAV} = 27 \text{ A}$

$V_T = 1.27 \text{ V}$

Phase leg

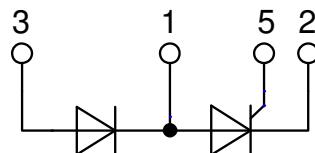
Part number

MCD26-16io8B



Backside: isolated

E72873



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al₂O₃-ceramic

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: TO-240AA

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Terms & Conditions of usage:

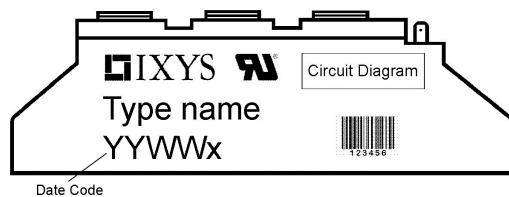
The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office. Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

- to perform joint risk and quality assessments;
- the conclusion of quality agreements;
- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

Rectifier			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1700	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1600	V
$I_{R/D}$	reverse current, drain current	$V_{R/D} = 1600 V$ $V_{R/D} = 1600 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		100 3	μA mA
V_T	forward voltage drop	$I_T = 40 A$	$T_{VJ} = 25^\circ C$		1.27	V
		$I_T = 80 A$			1.64	V
		$I_T = 40 A$	$T_{VJ} = 125^\circ C$		1.27	V
		$I_T = 80 A$			1.65	V
I_{TAV}	average forward current	$T_C = 85^\circ C$	$T_{VJ} = 125^\circ C$		27	A
$I_{T(RMS)}$	RMS forward current	180° sine			42	A
V_{T0}	threshold voltage	r_T slope resistance } for power loss calculation only	$T_{VJ} = 125^\circ C$		0.85	V
	slope resistance				11	$m\Omega$
R_{thJC}	thermal resistance junction to case				0.88	K/W
R_{thCH}	thermal resistance case to heatsink			0.20		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		115	W
I_{TSM}	max. forward surge current	$t = 10 ms; (50 Hz)$, sine	$T_{VJ} = 45^\circ C$		520	A
		$t = 8,3 ms; (60 Hz)$, sine	$V_R = 0 V$		560	A
		$t = 10 ms; (50 Hz)$, sine	$T_{VJ} = 125^\circ C$		440	A
		$t = 8,3 ms; (60 Hz)$, sine	$V_R = 0 V$		475	A
I^2t	value for fusing	$t = 10 ms; (50 Hz)$, sine	$T_{VJ} = 45^\circ C$		1.35	kA^2s
		$t = 8,3 ms; (60 Hz)$, sine	$V_R = 0 V$		1.31	kA^2s
		$t = 10 ms; (50 Hz)$, sine	$T_{VJ} = 125^\circ C$		970	A^2s
		$t = 8,3 ms; (60 Hz)$, sine	$V_R = 0 V$		940	A^2s
C_J	junction capacitance	$V_R = 400 V$ $f = 1 MHz$	$T_{VJ} = 25^\circ C$	22		pF
P_{GM}	max. gate power dissipation	$t_p = 30 \mu s$	$T_C = 125^\circ C$		10	W
		$t_p = 300 \mu s$			5	W
P_{GAV}	average gate power dissipation				0.5	W
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 125^\circ C$; $f = 50 Hz$	repetitive, $I_T = 45 A$		150	$A/\mu s$
		$t_p = 200 \mu s$; $di_G/dt = 0.45 A/\mu s$				
		$I_G = 0.45 A$; $V = \frac{2}{3} V_{DRM}$	non-repet., $I_T = 27 A$		500	$A/\mu s$
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^\circ C$		1000	$V/\mu s$
		$R_{GK} = \infty$; method 1 (linear voltage rise)				
V_{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^\circ C$		1.5	V
			$T_{VJ} = -40^\circ C$		1.6	V
I_{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^\circ C$		100	mA
			$T_{VJ} = -40^\circ C$		200	mA
V_{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^\circ C$		0.2	V
I_{GD}	gate non-trigger current				10	mA
I_L	latching current	$t_p = 10 \mu s$ $I_G = 0.45 A$; $di_G/dt = 0.45 A/\mu s$	$T_{VJ} = 25^\circ C$		450	mA
I_H	holding current	$V_D = 6 V$ $R_{GK} = \infty$	$T_{VJ} = 25^\circ C$		200	mA
t_{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25^\circ C$		2	μs
		$I_G = 0.45 A$; $di_G/dt = 0.45 A/\mu s$				
t_q	turn-off time	$V_R = 100 V$; $I_T = 20 A$; $V = \frac{2}{3} V_{DRM}$ $T_{VJ} = 100^\circ C$ $di/dt = 10 A/\mu s$ $dv/dt = 20 V/\mu s$ $t_p = 200 \mu s$		150		μs

Package TO-240AA			Ratings		
Symbol	Definition	Conditions	min.	typ.	max.
I_{RMS}	RMS current	per terminal			200 A
T_{VJ}	virtual junction temperature		-40		125 °C
T_{op}	operation temperature		-40		100 °C
T_{stg}	storage temperature		-40		125 °C
Weight				81	g
M_D	mounting torque		2.5		4 Nm
M_T	terminal torque		2.5		4 Nm
$d_{Spp/App}$	creepage distance on surface / striking distance through air		terminal to terminal	13.0	9.7 mm
$d_{Spb/Apb}$			terminal to backside	16.0	16.0 mm
V_{ISOL}	isolation voltage	t = 1 second t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA		3600 V 3000 V



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCD26-16io8B	MCD26-16io8B	Box	36	453277

Similar Part	Package	Voltage class
MCMA35PD1600TB	TO-240AA-1B	1600
MCMA50PD1600TB	TO-240AA-1B	1600

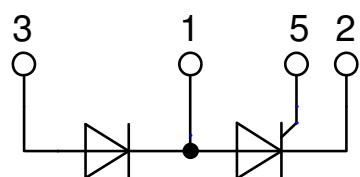
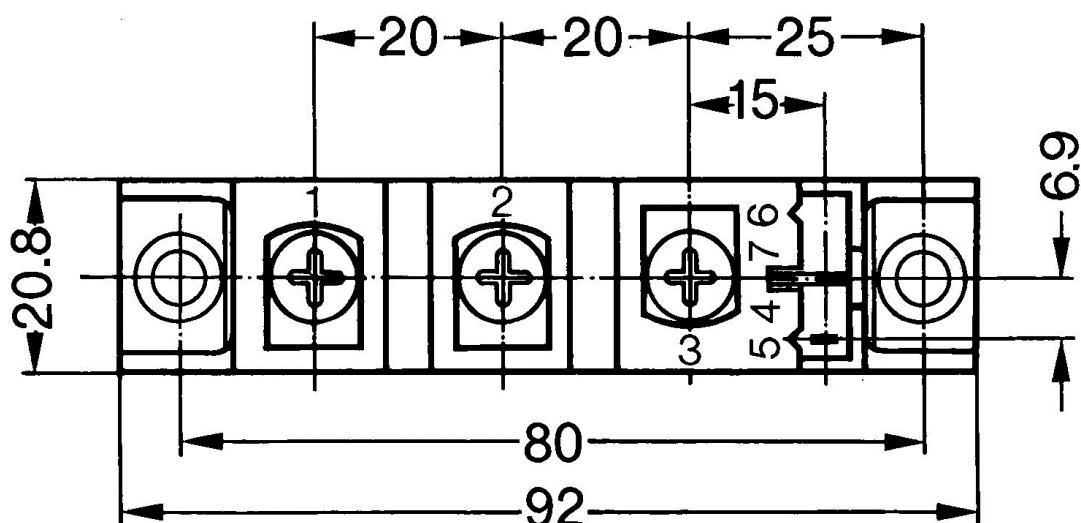
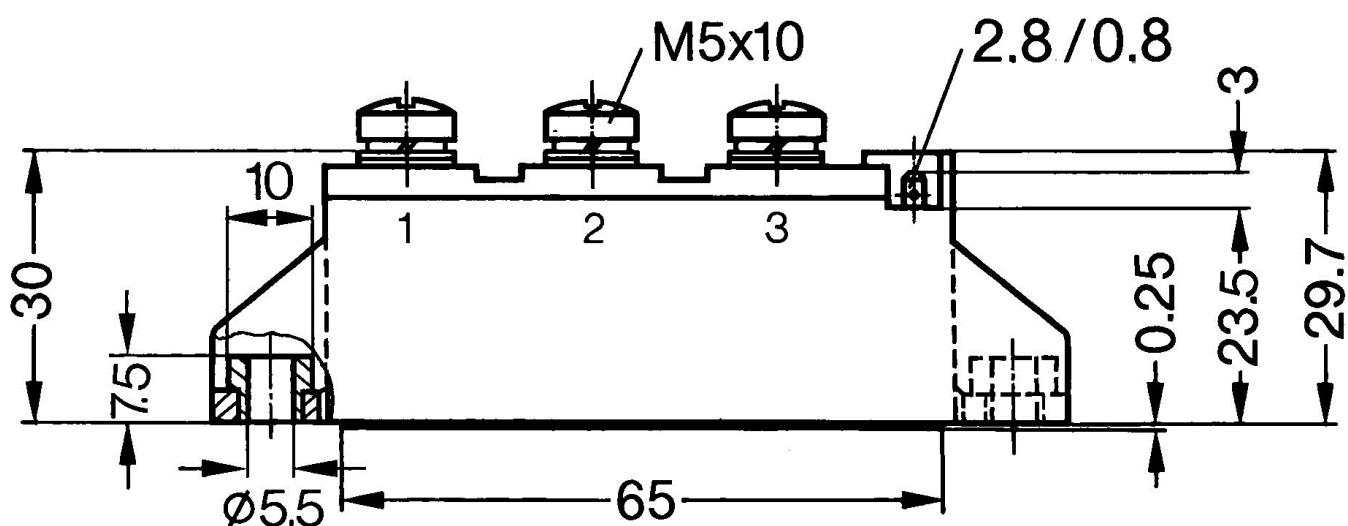
Equivalent Circuits for Simulation

* on die level

$T_{VJ} = 125$ °C

	Thyristor	
$V_{0\max}$	threshold voltage	0.85 V
$R_{0\max}$	slope resistance *	9.8 mΩ

Outlines TO-240AA



Thyristor

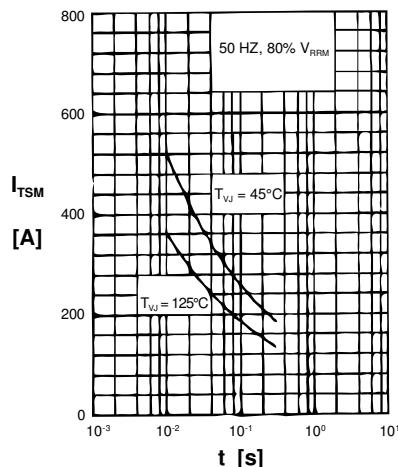


Fig. 1 Surge overload current
 I_{TSM} : Crest value, t : duration

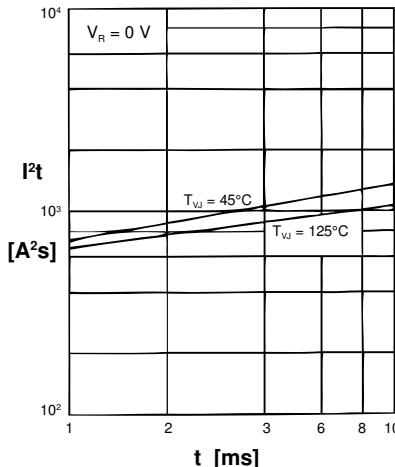


Fig. 2 I^2t versus time (1-10 ms)

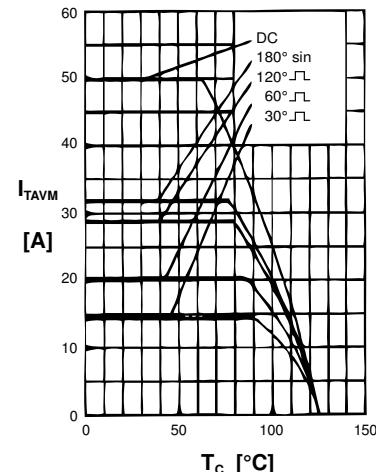


Fig. 3 Max. forward current
at case temperature

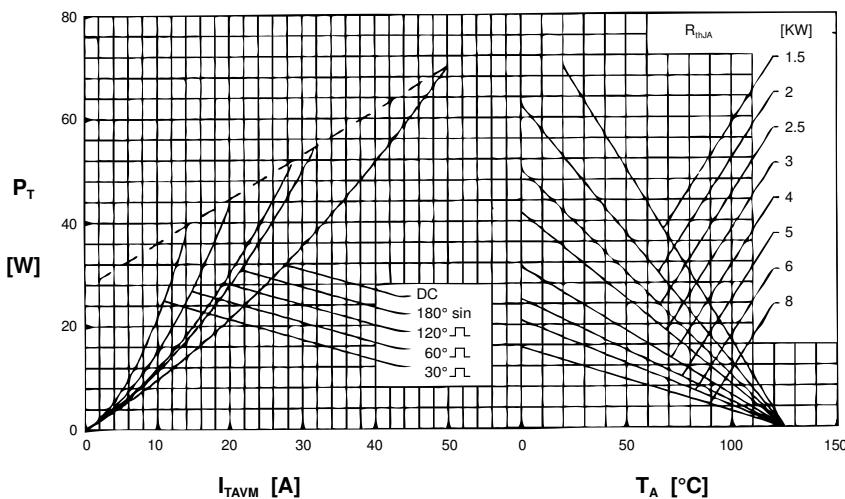


Fig. 4 Power dissipation versus onstate current & ambient temp. (per thyristor)

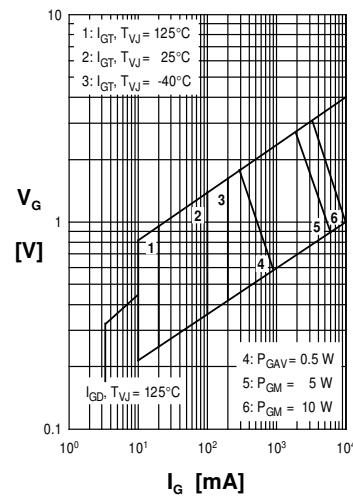


Fig. 5 Gate trigger charact.

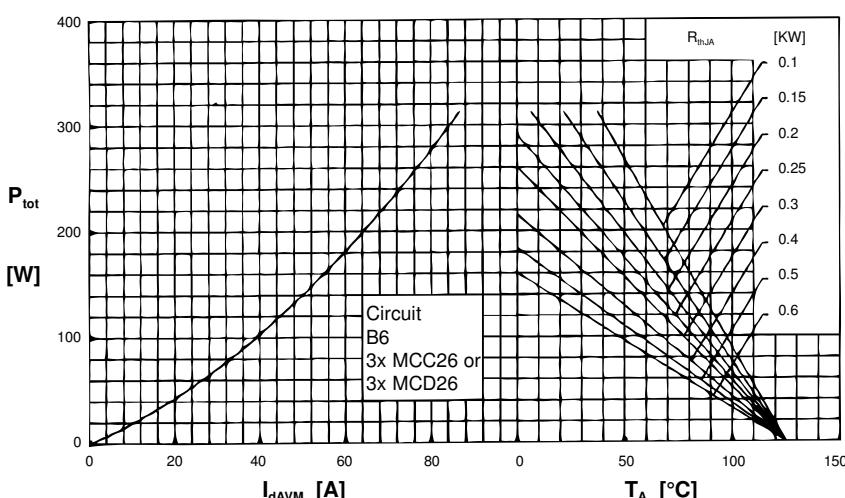


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

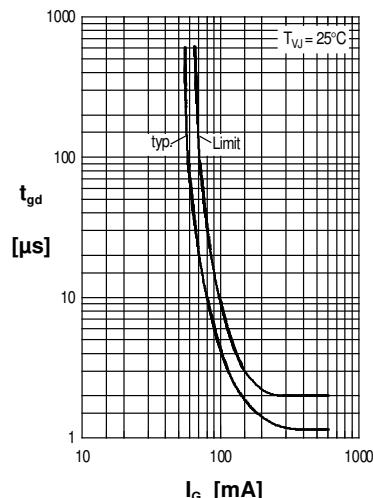


Fig. 7 Gate trigger delay time

Rectifier

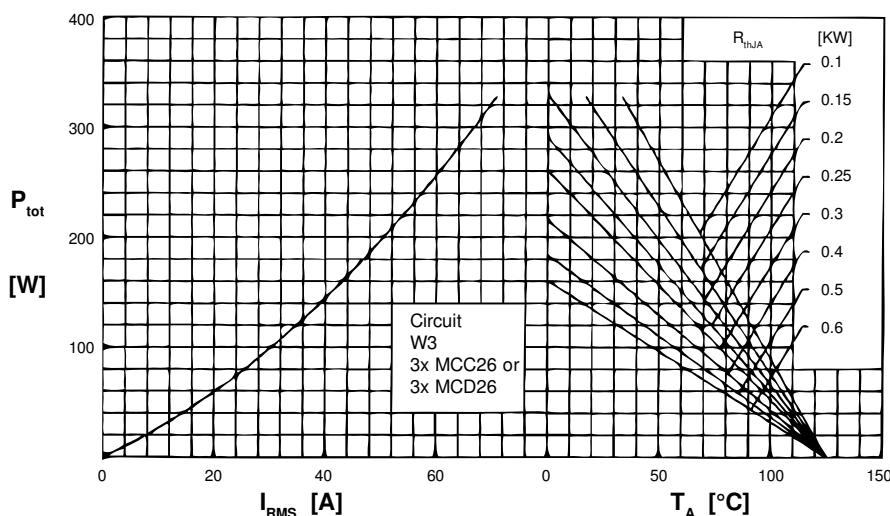


Fig. 8 Three phase AC-controller: Power dissipation vs. RMS output current and ambient temperature

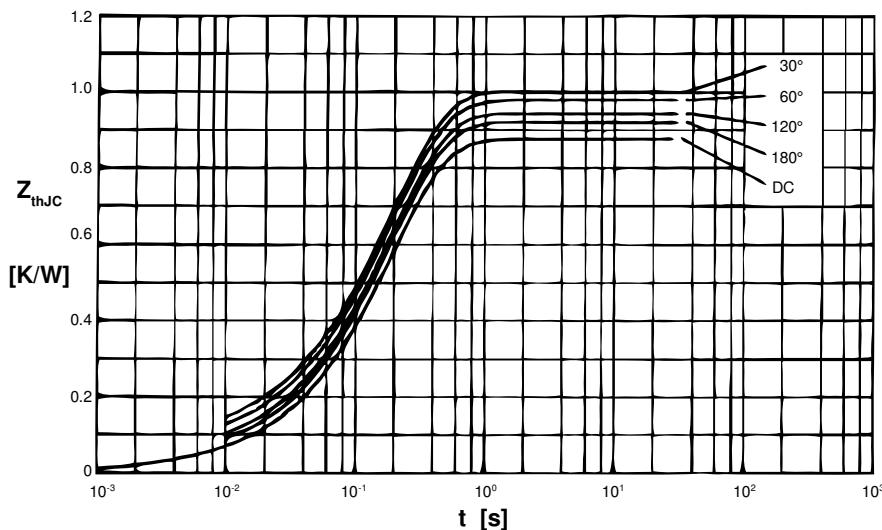


Fig. 9 Transient thermal impedance junction to case (per thyristor)

R_{thJC} for various conduction angles d :	
d	R_{thJC} [K/W]
DC	0.88
180°	0.92
120°	0.95
60°	0.98
30°	1.01

Constants for Z_{thJC} calculation:		
i	R_{thi} [K/W]	t_i [s]
1	0.019	0.0031
2	0.029	0.0216
3	0.832	0.1910

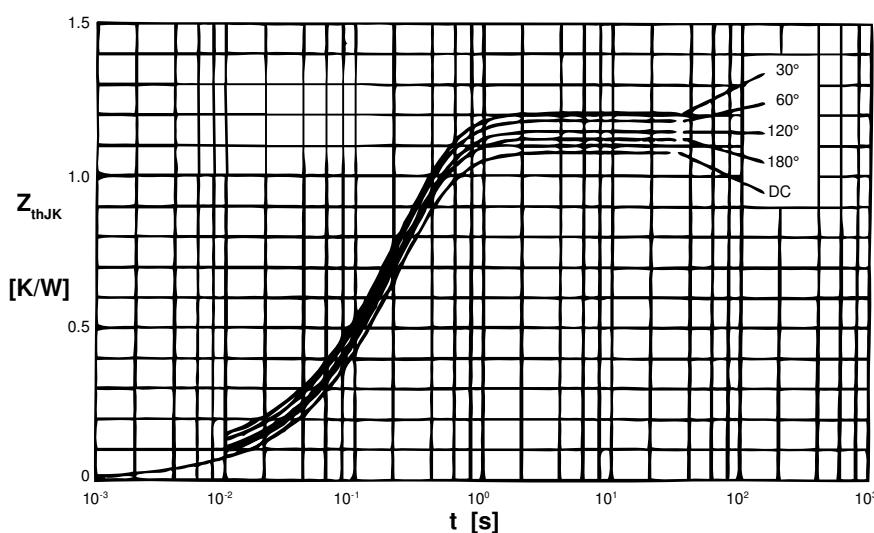


Fig. 10 Transient thermal impedance junction to heatsink (per thyristor)

R_{thJK} for various conduction angles d :	
d	R_{thJK} [K/W]
DC	1.08
180°	1.12
120°	1.15
60°	1.18
30°	1.21

Constants for Z_{thJK} calculation:		
i	R_{thi} [K/W]	t_i [s]
1	0.019	0.0031
2	0.029	0.0216
3	0.832	0.1910
4	0.200	0.4500

V _{RSM} V _{DRM}	V _{RRM} V _{DRM}	(dv/ dt) _{cr} V/μs	I _{TRMS} (maximum value for continuous operation)			
			75 A			
			I _{TAV} (sin. 180; T _{case} = 68 °C)			
			48 A			
500	400	500	—	—	SKKH 41/04 D	—
700	600	500	SKKT 41/06 D	SKKT 42/06 D	SKKH 41/06 D	SKKH 42/06 D
900	800	500	SKKT 41/08 D	SKKT 42/08 D ¹⁾	SKKH 41/08 D	SKKH 42/08 D
1300	1200	1000	SKKT 41/12 E	SKKT 42/12 E ¹⁾	SKKH 41/12 E	SKKH 42/12 E
1500	1400	1000	SKKT 41/14 E	SKKT 42/14 E ¹⁾	SKKH 41/14 E	SKKH 42/14 E
1700	1600	1000	SKKT 41/16 E	SKKT 42/16 E ¹⁾	SKKH 41/16 E	SKKH 42/16 E
1900	1800	1000	SKKT 41/18 E	SKKT 42/18 E ¹⁾	SKKH 41/18 E	SKKH 42/18 E
2100	2000	1000	SKKT 41/20 E	SKKT 42/20 E ¹⁾	—	—
2300	2200	1000	SKKT 41/22 E	SKKT 42/22 E ¹⁾	—	—

SEMIPACK® 1 Thyristor / Diode Modules

SKKT 41 SKKH 41
 SKKT 42 SKKH 42
 SKKT 42B SKKL 42²⁾



Symbol	Conditions	SKKT 41 SKKH 41	SKKT 42 SKKT 42B	SKKH 42	Units
I _{TAV}	sin. 180; T _{case} = 74 °C T _{case} = 85 °C	48		A	
I _D	B2/B6 T _{amb} = 45 °C; P 3/180 T _{amb} = 35 °C; P 3/180 F	40 50 / 60 85 / 110 110 / 3 x 85		A	
I _{RMS}	W1/W3 T _{amb} = 35 °C; P 3/180 F			A	
I _{TSM}	T _{vj} = 25 °C; 10 ms T _{vj} = 125 °C; 10 ms	1 000		A	
i ² t	T _{vj} = 25 °C; 8,3 ... 10 ms T _{vj} = 125 °C; 8,3 ... 10 ms	850 5 000 3 600		A ² s A ² s	
t _{gd}	T _{vj} = 25 °C; I _G = 1 A dI _G /dt = 1 A/μs	1		μs	
t _{gr}	V _D = 0,67 · V _{DRM}	2		μs	
(di/dt) _{cr}	T _{vj} = 125 °C	150		A/μs	
t _q	T _{vj} = 125 °C	typ. 80		μs	
I _H	T _{vj} = 25 °C; typ./max.	150 / 250		mA	
I _L	T _{vj} = 25 °C; R _G = 33 Ω; typ./max.	300 / 600		mA	
V _T	T _{vj} = 25 °C; I _T = 200 A	max. 1,95		V	
V _{T(TO)}	T _{vj} = 125 °C	1		V	
r _T	T _{vj} = 125 °C	4,5		mΩ	
I _{DD} ; I _{RD}	T _{vj} = 125 °C; V _{RD} = V _{RRM} V _{DD} = V _{DRM}	max. 15 ³⁾		mA	
V _{GT}	T _{vj} = 25 °C; d.c.	3		V	
I _{GT}	T _{vj} = 25 °C; d.c.	150		mA	
V _{GD}	T _{vj} = 125 °C; d.c.	0,25		V	
I _{GD}	T _{vj} = 125 °C; d.c.	6		mA	
R _{thjc}	cont. sin. 180 rec. 120	0,65 / 0,33 0,69 / 0,35 0,73 / 0,37 0,2 / 0,1 — 40 ... + 125 — 40 ... + 125		°C/W °C/W °C/W °C/W °C °C	
R _{thch}	per thyristor / per module				
T _{vj}					
T _{stg}					
V _{isol}	a. c. 50 Hz; r.m.s.; 1 s/1 min	3600 / 3000		V~	
M ₁	to heatsink	5 (44 lb. in.) ± 15 % ⁴⁾		Nm	
M ₂	to terminals	3 (26 lb. in.) ± 15 %		Nm	
a		5 · 9,81		m/s ²	
w	approx.	95		g	
Case	→ page B 1 – 95	SKKT 41: A 5 SKKH 41: A 6 SKKH 42: A 47	SKKL 42: A 59 SKKT 42: A 46 SKKT 42B: A 48		

Features

- Heat transfer through aluminium oxide ceramic isolated metal baseplate
- Hard soldered joints for high reliability
- UL recognized, file no. E 63 532

Typical Applications

- DC motor control (e.g. for machine tools)
- AC motor soft starters
- Temperature control (e.g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)

¹⁾ Also available in SKKT 42 B configuration (case A 48)

²⁾ SKKL 42 available on request

³⁾ /20 E, /22 E max. 30 mA

⁴⁾ See the assembly instructions

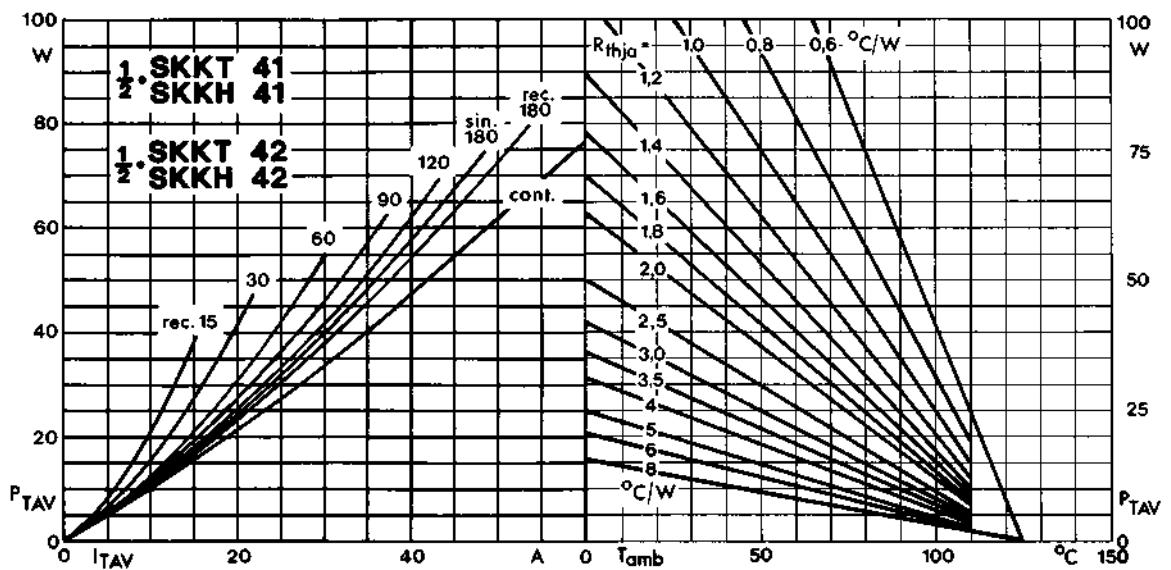


Fig. 1 Power dissipation per thyristor vs. on-state current and ambient temperature

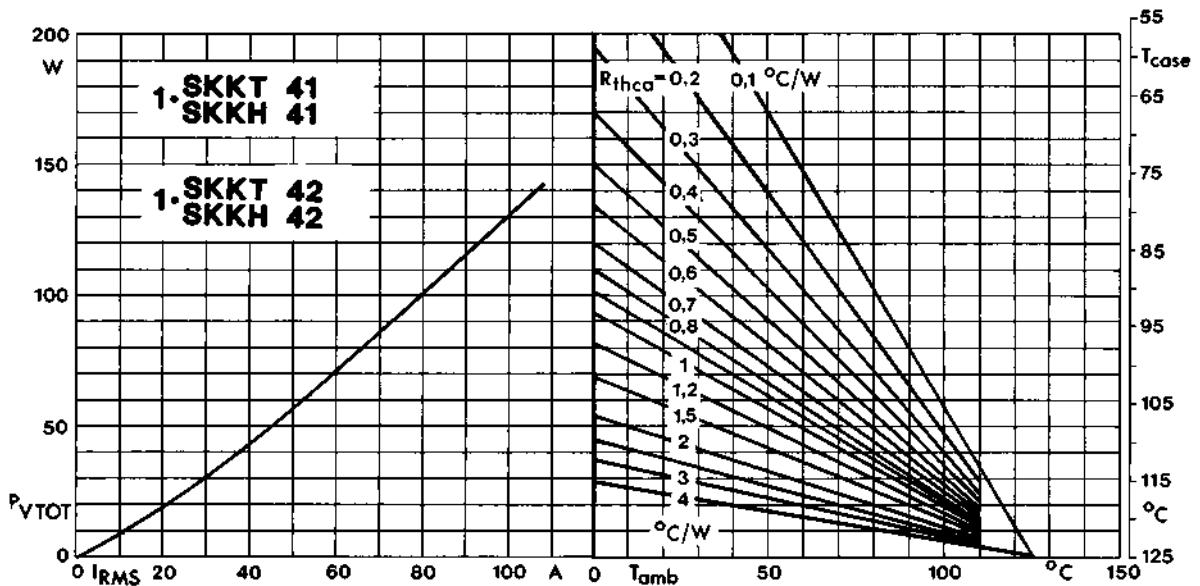


Fig. 2 Power dissipation per module vs. rms current and case temperature

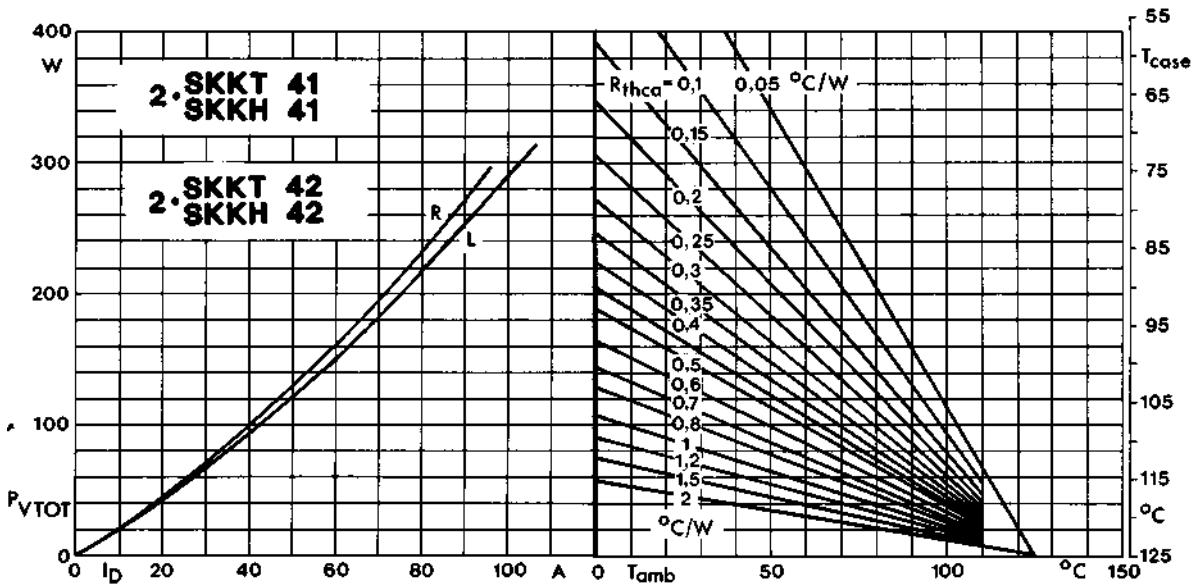


Fig. 3 Power dissipation of two modules vs. direct current and case temperature

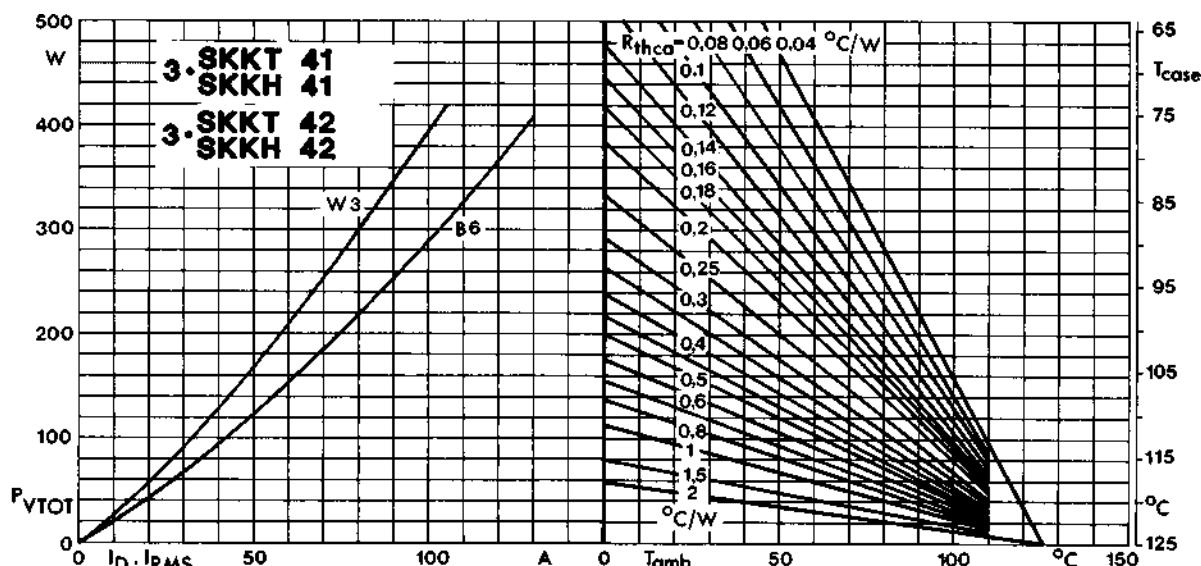


Fig. 4 Power dissipation of three modules vs. direct and rms current and case temperature

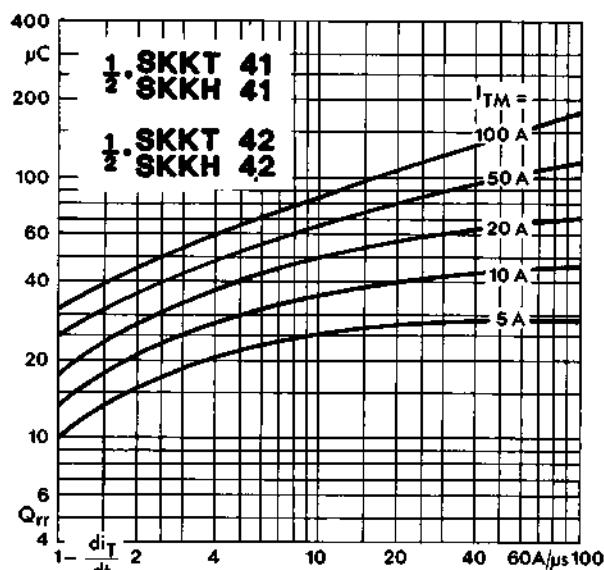


Fig. 5 Recovered charge vs. current decrease

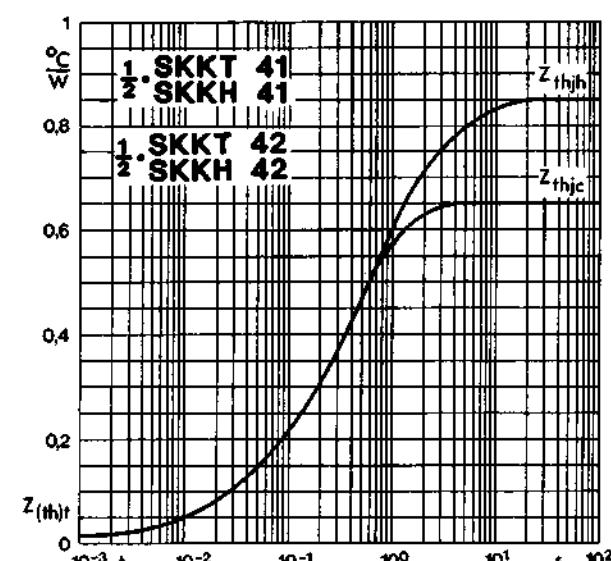


Fig. 6 Transient thermal impedance vs. time

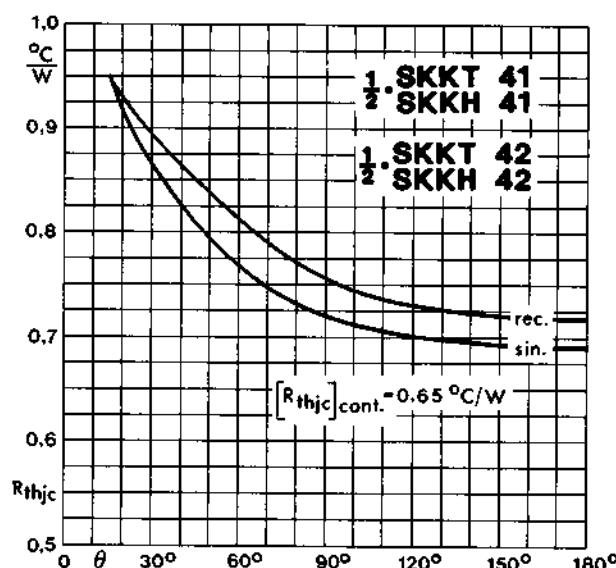


Fig. 7 Thermal resistance vs. conduction angle

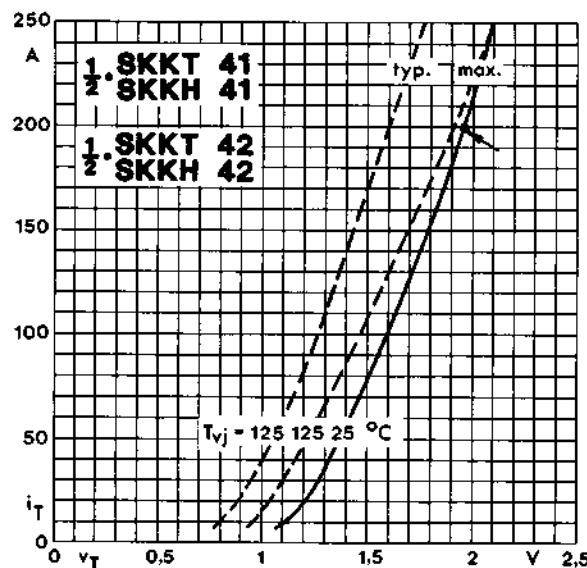


Fig. 8 On-state characteristics

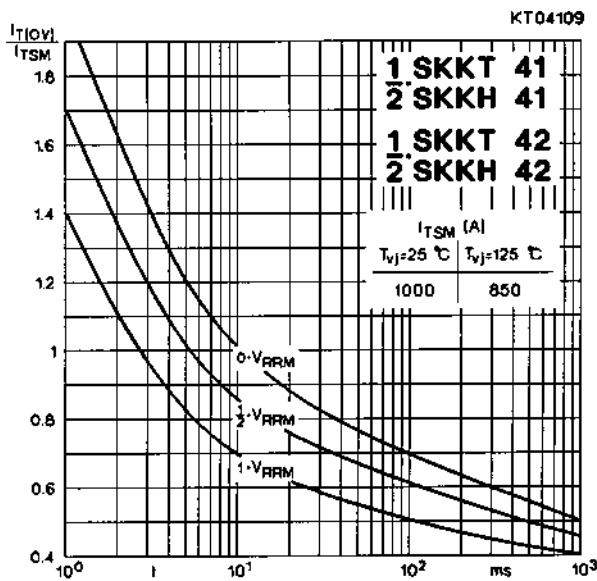


Fig. 9 Surge overload current vs. time

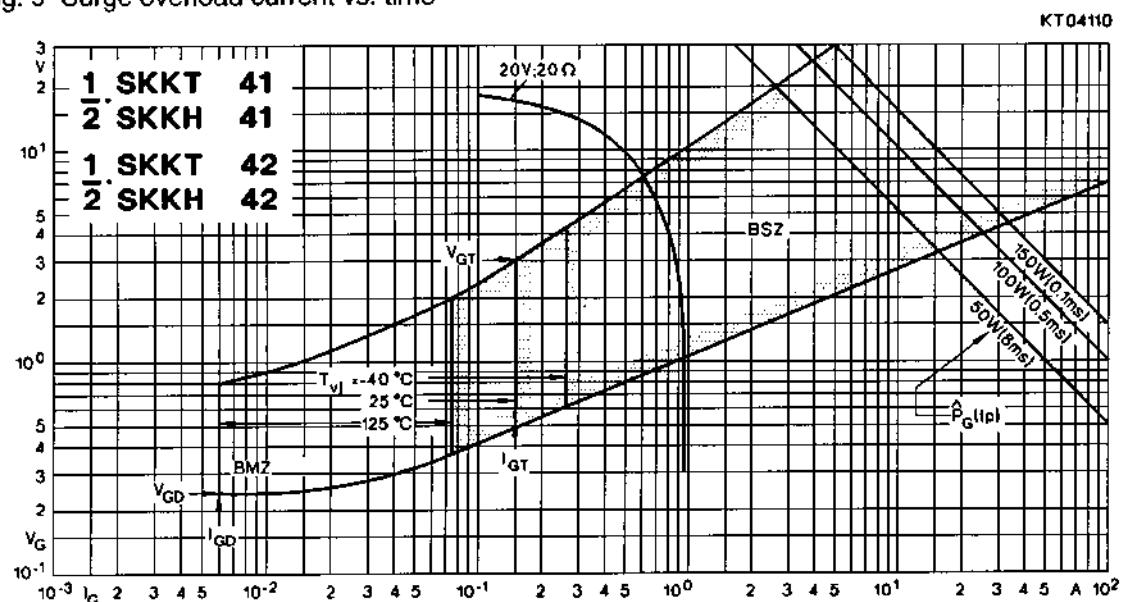


Fig. 10 Gate trigger characteristics

модуль semikron, igbt, мост диодный Минск +375447584780
www.fotorele.net www.tiristor.by радиодетали, электронные компоненты
email minsk17@tut.by tel.+375 29 758 47 80 мтс

Мы не работаем с частными (физическими) лицами.
Мы работаем только с юридическими лицами(организациями) и ИП и только по безналичному расчёту.
каталог, описание, технические, характеристики, datasheet, параметры, маркировка, габариты, фото

КАТАЛОГ SEMIKRON 2017/2018 МИНСК

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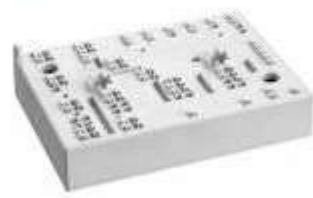
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Full SiC



Hybrid SiC



SKiiP



SEMIPACK



SEMITOP

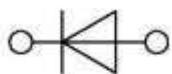
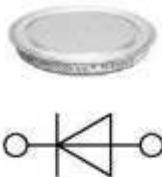


SEMIX

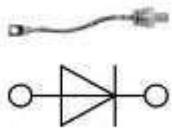


SEMISTART





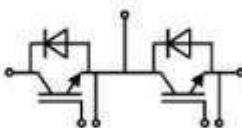
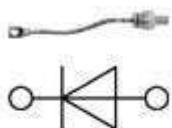
Power Bridge Rectifiers



SEMISTACK Classics



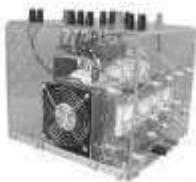
SEMPONT



SEMIX



SEMITEACH



PT 22b3 RoHS

Pulse Transformer

Part Number: 97492890

Manufacturer: SEMIKRON

[datasheet](#)

[Product Details >>](#)

● Current delivery time approx. 10 weeks



Axial fan 230V 119x38m 150m³/h

Fan

V 230 V

Part Number: 30031061

Manufacturer: SEMIKRON

[datasheet](#)



Thermal paste P12

Thermal paste

Part Number: 31867700

Manufacturer: SEMIKRON

 [datasheet](#)